

L2: Entry 3 of 4

File: JPAB

Oct 19, 2001

PUB-NO: JP02001291760A  
DOCUMENT-IDENTIFIER: JP 2001291760 A  
TITLE: METHOD AND TAPE FOR PEELING

PUBN-DATE: October 19, 2001

INVENTOR-INFORMATION:

NAME

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COUNTRY

INT-CL (IPC): H01 L 21/68; B65 H 41/00; H01 L 21/304; H01 L 21/301

ABSTRACT:

PROBLEM TO BE SOLVED: To provide a peeling method in which a substance can be prevented from breakage which is generated when the substance is peeled from a fixing tape for fixing the substance at such a machining duration as a back grind step or a dicing step for a semiconductor wafer.

SOLUTION: This peeling method has a feature of suctioning (reducing a pressure) from other surface of a tape for peeling when a machining substance is attached with the tape for peeling, especially porous member is preferably used as the tape for peeling and the machining substance is attached, at the time of peeling the machining substance from a fixing tape for machining.

DERWENT-ACC-NO: 2002-008068  
DERWENT-WEEK: 200201  
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*Tsuchihashi et al*

TITLE: Thin processed product peeling method involves peeling processed object adhered to porous polymer film tape

PRIORITY-DATA: 2000JP-0027347 (January 31, 2000)

## PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input checked="" type="checkbox"/> JP 2001291760 A	October 19, 2001		004	H01L021/68

INT-CL (IPC): B65 H 41/00; H01 L 21/301; H01 L 21/304; H01 L 21/68

ABSTRACTED-PUB-NO: JP2001291760A  
BASIC-ABSTRACT:

NOVELTY - Object to be processed is adhered to tape made of porous polymer film, by suction technique and is removed after processing.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for peeling tape.

USE - For thin products such as integrated circuit card. Also for semiconductor wafer during back-grind or dicing process.

ADVANTAGE - Damage of goods to be processed is prevented.

L14 ANSWER 33 OF 50 CAPLUS COPYRIGHT 2005 ACS on STN

Full Text

AN 2001:762672 CAPLUS

TI Exfoliation method and tape for exfoliation [Machine Translation].

IN Tsuchihashi, Akihiko; Iketani, Takuji; Kuwahara, Noriko

PA Hitachi Chemical Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 4 pp.

CODEN: JKXXAF

STN Columbus

DT Patent

LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2001291760	A2	20011019	JP 2000-343905	20001110
PRAI	JP 2000-27347	A	20000131		

AB [Machine Translation of Descriptors]. As for this invention purpose when processing like back grinding process and dicing process of the semiconductor wafer the occasion where that material is exfoliated from the fixed tape because the material is locked there are times when the exfoliation method of being possible to prevent the damage of the material which occurs is offered. When processing (decompression) the exfoliation method of designating that makes the processing material the tape for exfoliation come in contact the material which is processed from the tape for fixing is exfoliated at the time of, especially is desirable, uses the porous material as the tape for exfoliation, from the other aspect of the tape for exfoliation absorbs makes the processing material come in contact at the time of, as feature.